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Part Number: [0736446216](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location B, Polarizing Key Position N/A, 144 Circuits

Documents:
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	None
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.375
Polarized to PCB	No
Stackable	No



image - Reference only

Series

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73644Series](#)

Mates With
[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
HDM® Backplane Insertion Signal Contact Tool	0621001400
HDM® Backplane Insertion Head for 144 Positions Extraction Tool	0622005703 0621001000

Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Sales Drawing	SD-73644-003
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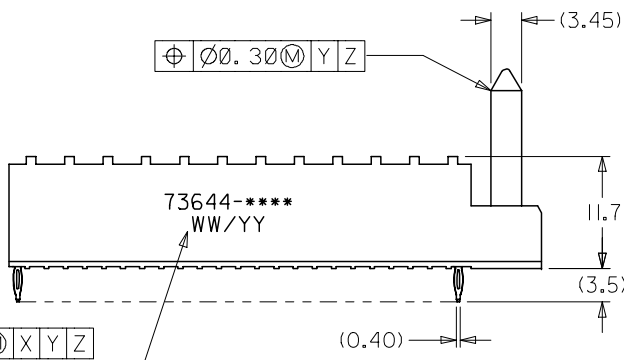
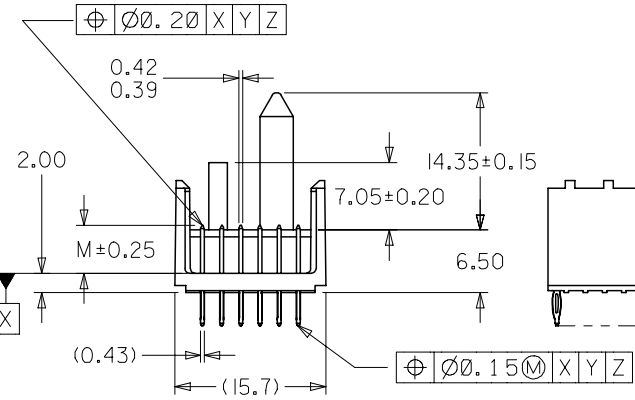
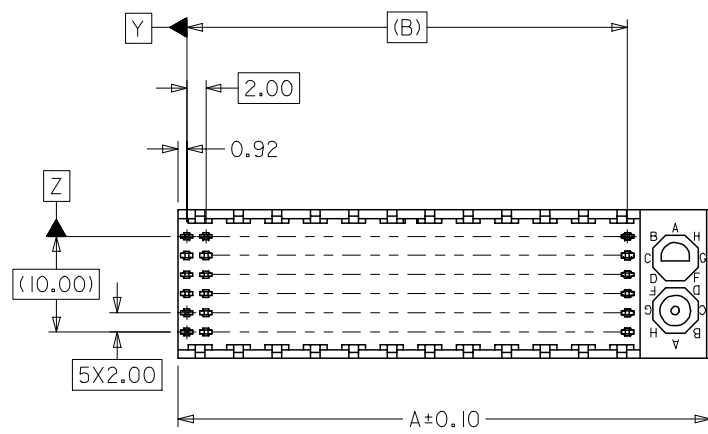
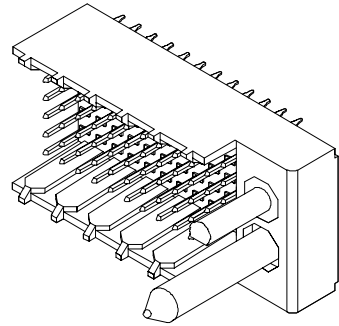
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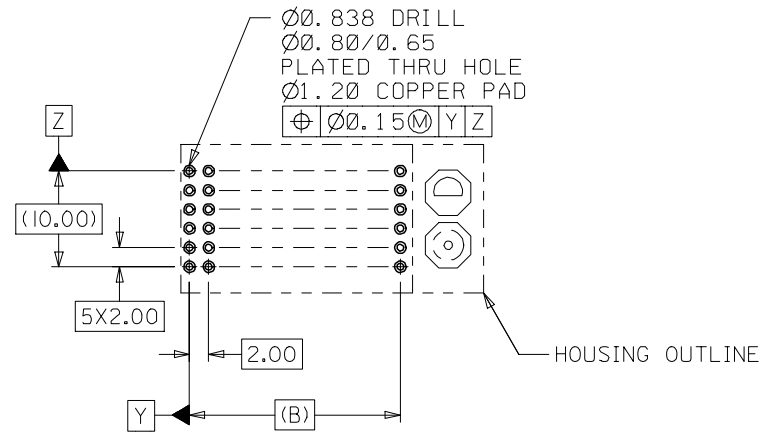
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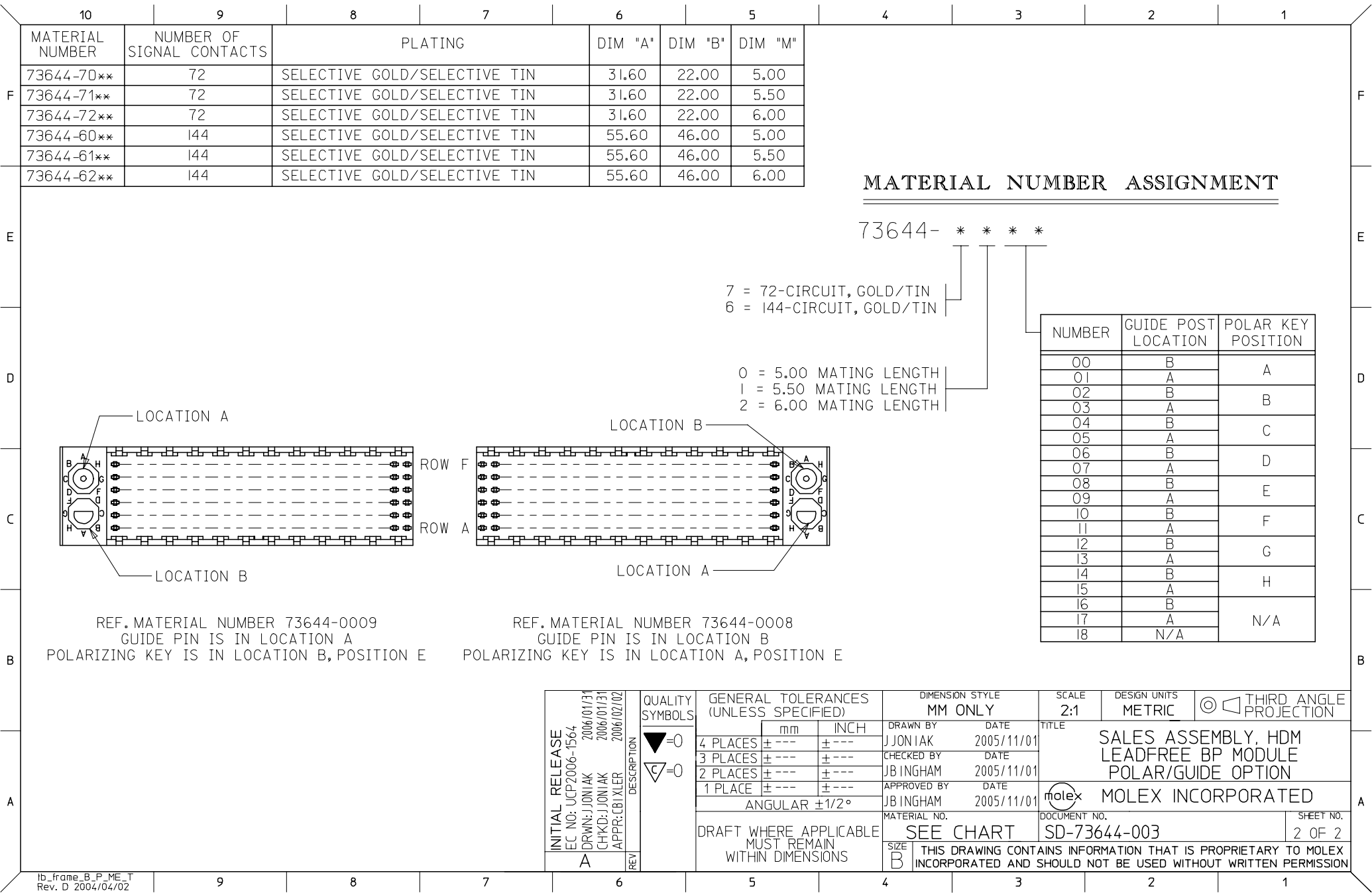
SEE NOTE 7

- NOTES:**
1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE.
 2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MIN. THICKNESS; SELECTIVE TIN (Sb) IN TAIL AREA; NICKEL (Ni) OVERALL.
 3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
 4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
 5. FOR SPECIFIC MATERIAL NUMBERS, REFER TO SHEET 2.
 6. PACKAGE PER PK-70873-0818.
 7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

INITIAL RELEASE EC NO: UCP2006-1564 DRWN: JJONIAK 2006/01/31 CHKD: JBINGHAM 2006/01/31 APPR: CBI XLER 2006/02/02	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY JJONIAK 2005/11/01		TITLE SALES ASSEMBLY, HDM LEADFREE BP MODULE POLAR/GUIDE OPTION	
			4 PLACES	± ---	± ---	CHECKED BY JBINGHAM 2005/11/01			
			3 PLACES	± ---	± ---	APPROVED BY JBINGHAM 2005/11/01			
			2 PLACES	± ---	± ---	MATERIAL NO. SEE SHEET 2			
REV A			1 PLACE	± ---	± ---	MOLEX INCORPORATED		DOCUMENT NO. SD-73644-003	SHEET NO. 1 OF 2
			ANGULAR ±1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



Данный компонент на территории Российской Федерации

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<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

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